

### **Amendments to the Specification**

Please add the following new paragraphs after paragraph [0054]:

[0054.1] FIG. 35 is an exploded isometric view of another embodiment IC package unit incorporating ball-grid array packages on a carrier with a ball-grid array.

[0054.2] FIG. 36 is an isometric view of the assembled embodiment shown in FIG. 35.

Please add the following new paragraph after paragraph [0073]:

[0073.1] Referring now to FIG. 35, a seventh embodiment electronic module utilizes a sixth embodiment carrier 3501 designed for the mounting of multiple ball-grid array IC packages 3502 A-D. Such packages may employ pads, rather than leads, to make connection from a semiconductor chip to the external world. This carrier 3501 incorporates a ball-grid array 3503, which is solder reflowable for mounting to pads on a printed circuit board. Each of the ball-grid array IC packages 3502 A-D may have a plurality of connection elements, which may, for example include pads on each of which a metal (e.g., gold) ball 3505 may be bonded or solder reflow attached. Each of the ball-grid array IC packages 3502 may be mounted on the carrier 3501 and each of the balls 3505 may be physically and electrically bonded to a corresponding pad on the carrier 3501. Bonding can be via solder reflow, via vibrational energy input, or any other known technique. The mounting process creates a multiple-package ball-grid array package unit 3601, shown in FIG. 36.